### Vishay

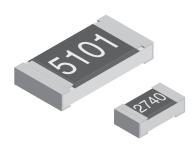


AUTOMOTIVE

HALOGEN

FREE

# **High Stability Thin Film Flat Chip Resistors**



TNPW e3 precision thin film flat chip resistors are the perfect choice for most fields of modern electronics where highest reliability and stability is of major concern. Typical applications include test and measuring equipment, medical equipment, industrial, and automotive.

#### **FEATURES**

- Low temperature coefficient and tight tolerances (± 0.1 %; ± 10 ppm/K)
- Superior moisture resistivity ≤ 0.25 % (85 °C; 56 days; 85 % RH)
- Excellent overall stability at different environmental conditions ≤ 0.05 % (1000 h rated power at 70 °C)
- AEC-Q200 qualified (sizes 0402 to 1206)
- · Waste gas resistant
- Material categorization: For definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

#### **APPLICATIONS**

- · Test and measuring equipment
- · Medical equipment
- · Industrial equipment
- Automotive

STANDARD EL	ECTRICAL	SPECIFIC <i>E</i>	TIONS					
DESCRIPTION	TNPW0402 e3	TNPW0603 e3	TNPW0805 e3	TNPW1206 e3	TNPW1210 e3 (1)	TNPW2010 e3	TNPW2512 e3 (1)	
Metric size	RR 1005M	RR 1608M	RR 2012M	RR 3216M	RR 3225M	RR 5025M	RR 6332M	
Resistance range	10 $\Omega$ to 100 k $\Omega$	10 $\Omega$ to 332 $\text{k}\Omega$	10 $\Omega$ to 1 M $\Omega$	10 $\Omega$ to 2 M $\Omega$	10 $\Omega$ to 3.01 M $\Omega$	10 $\Omega$ to 4.99 M $\Omega$	10 $\Omega$ to 8.87 M $\Omega$	
Resistance tolerance			:	± 1 %; ± 0.5 %;	± 0.1 %			
Temperature coefficent		± 50 ppm/K; ± 2	5 ppm/K; ± 15 p	pm/K; ± 10 ppm	/K	± 50 ppm/K	; ± 25 ppm/K	
Rated dissipation, $P_{70}^{(2)}$	0.063 W	0.1 W	0.125 W	0.25 W	0.33 W	0.4 W	0.5 W	
Operating voltage, <i>U</i> <sub>max.</sub> AC/DC	50 V	75 V	150 V	200 V	200 V	300 V	300 V	
Permissible film temperature, $\vartheta_{\rm F}$ max.		155 °C						
Operating temperature range			- :	55 °C to 125 °C	(155 °C)			
Thermal resistance (3)	870 K/W	550 K/W	440 K/W	220 K/W	170 K/W	140 K/W	110 K/W	
Max. resistance change at $P_{70}$ ; $\Delta R/R$ :	10 $\Omega$ to 100 k $\Omega$	10 $\Omega$ to 332 k $\Omega$	10 $\Omega$ to 1 M $\Omega$	10 $\Omega$ to 2 M $\Omega$	10 $\Omega$ to 3.01 M $\Omega$	10 $\Omega$ to 4.99 M $\Omega$	10 $\Omega$ to 8.87 M $\Omega$	
1000 h	≤ 0.05 %	≤ 0.05 %	≤ 0.05 %	≤ 0.05 %	≤ 0.05 %	≤ 0.05 %	≤ 0.05 %	
8000 h	≤ 0.10 %	≤ 0.10 %	≤ 0.10 %	≤ 0.10 %	≤ 0.10 %	≤ 0.10 %	≤ 0.10 %	
225 000 h	≤ 0.30 %	≤ 0.30 % ≤ 0.30 % ≤ 0.30 % ≤ 0.30 % ≤ 0.30 %						
Insulation voltage:								
U <sub>ins</sub> 1 min	75 V	100 V	200 V	300 V	300 V	300 V	300 V	
Continuous	75 V	75 V	75 V	75 V	75 V	75 V	75 V	
Failure rate: FIT <sub>observed</sub>	≤ 0.1 x 10 <sup>-9</sup> /h	≤ 0.1 x 10 <sup>-9</sup> /h	≤ 0.1 x 10 <sup>-9</sup> /h	≤ 0.1 x 10 <sup>-9</sup> /h	≤ 0.1 x 10 <sup>-9</sup> /h	≤ 0.1 x 10 <sup>-9</sup> /h	≤ 0.1 x 10 <sup>-9</sup> /h	

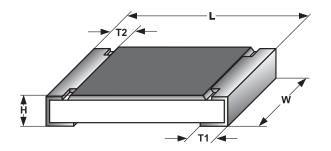
#### Notes

- TNPW 0402 without marking.
- (1) Size not specified in EN 140401-801.
- (2) Rated voltage  $\sqrt{P \times R}$ . The power dissipation on the resistor generates a temperature rise against the local ambient, depending on the heat flow support of the printed-circuit board (thermal resistance). Using advanced temperature level may require special considerations towards the choice of circuit board and solder material. The rated dissipation applies only if the permitted film temperature is not exceeded.
- (3) Measuring conditions in accordance with EN 140401-801.





### **DIMENSIONS**





DIMENSIONS AND MASS								
TYPE	L (mm)	W (mm)	H (mm)	T1/T2 (mm)	MASS (mg)			
TNPW0402 e3	$1.0 \pm 0.05$	$0.5 \pm 0.05$	$0.35 \pm 0.05$	$0.2 \pm 0.10$	0.65			
TNPW0603 e3	$1.6 \pm 0.10$	$0.85 \pm 0.10$	$0.45 \pm 0.10$	$0.3 \pm 0.20$	2			
TNPW0805 e3	$2.0 \pm 0.15$	$1.25 \pm 0.15$	$0.45 \pm 0.10$	$0.4 \pm 0.20$	5.5			
TNPW1206 e3	$3.2 \pm 0.15$	$1.6 \pm 0.15$	$0.55 \pm 0.10$	$0.5 \pm 0.25$	10			
TNPW1210 e3	$3.2 \pm 0.15$	$2.45 \pm 0.15$	$0.60 \pm 0.15$	$0.5 \pm 0.25$	16			
TNPW2010 e3	$5.0 \pm 0.15$	$2.5 \pm 0.15$	$0.60 \pm 0.15$	$0.6 \pm 0.25$	28			
TNPW2512 e3	$6.3 \pm 0.20$	$3.1 \pm 0.15$	$0.60 \pm 0.15$	$0.6 \pm 0.25$	39			

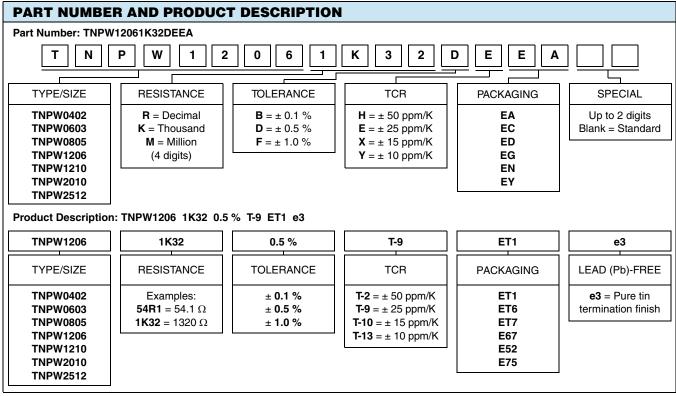
SOLDER PAD DIMENSIONS							
	REFLO	W SOLD	ERING	WAVE SOLDERING			
TYPE	a (mm)	b (mm)	l (mm)	a (mm)	b (mm)	l (mm)	
TNPW0402 e3	0.4	0.6	0.5	-	-	-	
TNPW0603 e3	0.5	0.9	1.0	0.9	0.9	1.0	
TNPW0805 e3	0.7	1.3	1.2	0.9	1.3	1.3	
TNPW1206 e3	0.9	1.7	2.0	1.1	1.7	2.3	
TNPW1210 e3	0.9	2.5	2.0	1.1	2.5	2.3	
TNPW2010 e3	1.0	2.5	3.9	1.2	2.5	3.9	
TNPW2512 e3	1.0	3.2	5.2	1.2	3.2	5.2	

TYPE	TCR	TOLERANCE	RESISTANCE	E-SERIES	
		± 1 %	10R to 100K	24; 96	
	± 50 ppm/K	± 0.5 %	10R to 100K	24; 192	
		± 0.1 %	47R to 100K		
TNDW0400 a0		± 1 %	10R to 100K	24; 96	
TNPW0402 e3	± 25 ppm/K	± 0.5 %	10R to 100K		
		± 0.1 %		04: 100	
	± 15 ppm/K	± 0.1 %	47R to 100K	24; 192	
	± 10 ppm/K	± 0.1 %			
		± 1 %	10R to 332K	24; 96	
	± 50 ppm/K	± 0.5 %	10R to 332K	24; 192	
TNPW0603 e3		± 0.1 %	10H to 332K	24, 192	
		± 1 %	10R to 332K	24; 96	
	± 25 ppm/K	± 0.5 %	10R to 332K	- 24; 192	
		± 0.1 %	10H to 332K		
	± 15 ppm/K	± 0.1 %	47R to 332K		
	± 10 ppm/K	± 0.1 %	47 H to 332 K		
		± 1 %	10R to 1M0	24; 96	
	± 50 ppm/K	± 0.5 %	10R to 1M0	24; 192	
		± 0.1 %		,	
TNPW0805 e3		± 1 %	10R to 1M0	24; 96	
1141 VV0003 <del>C</del> 3	± 25 ppm/K	± 0.5 %	10R to 1M0		
		± 0.1 %	TOTA TO TIMO	24; 192	
	± 15 ppm/K	± 0.1 %	47R to 1M0	24, 132	
	± 10 ppm/K	± 0.1 %			
		± 1 %	10R to 2M0	24; 96	
	± 50 ppm/K	± 0.5 %	10R to 2M0	24; 192	
		± 0.1 %		,	
TNPW1206 e3		± 1 %	10R to 2M0	24; 96	
1141 44 1200 00	± 25 ppm/K	± 0.5 %	10R to 2M0		
		± 0.1 %	1011 to 21110	24; 192	
	± 15 ppm/K	± 0.1 %	47R to 2M0	24, 192	
	± 10 ppm/K	± 0.1 %	7/11 to 21010		

Document Number: 28758 Revision: 27-Jun-12 For technical questions, contact: thinfilmchip@vishay.com



TEMPERATURE COEFFICIENT AND RESISTANCE RANGE						
TYPE	TCR	TOLERANCE	RESISTANCE	E-SERIES		
		± 1 %	10R to 3M01	24; 96		
	± 50 ppm/K	± 0.5 %	10R to 3M01	04: 100		
		± 0.1 %	47R to 2M13	24; 192		
TNPW1210 e3		± 1 %	10R to 3M01	24; 96		
TNPW1210 e3	± 25 ppm/K	± 0.5 %	10R to 3M01			
		± 0.1 %		24: 102		
	± 15 ppm/K	± 0.1 %	47R to 2M13	24; 192		
	± 10 ppm/K	± 0.1 %				
		± 1 %	10R to 4M99	24; 96		
	± 50 ppm/K	± 0.5 %	10R to 4M99	24; 192		
TNPW2010 e3		± 0.1 %	47R to 1M0	24, 192		
11NF VV2010 e3		± 1 %	10R to 4M99	24; 96		
	± 25 ppm/K	± 0.5 %	10R to 4M99	04. 100		
		± 0.1 %	47R to 1M0	24; 192		
		± 1 %	10R to 8M87	24; 96		
TNPW2512 e3	± 50 ppm/K	± 0.5 %	10R to 8M87	04. 100		
		± 0.1 %	47R to 1M0	24; 192		
		± 1 %	10R to 8M87	24; 96		
	± 25 ppm/K	± 0.5 %	10R to 8M87	24: 102		
		± 0.1 %	47R to 1M0	24; 192		



• The product can be ordered using either the PART NUMBER or the PRODUCT DESCRIPTION.

www.vishay.com 338

For technical questions, contact: thinfilmchip@vishay.com



PACKAGING								
TYPE	CODE	QUANTITY	CARRIER TAPE	WIDTH	PITCH	REEL DIAMETER		
TNPW0402 e3	ET7 = ED	10 000		8 mm	2 mm	180 mm / 7"		
TNPW0603 e3 TNPW0805 e3 TNPW1206 e3 TNPW1210 e3	E52 = EN	1000 (1)	Paper tape acc. IEC 60286-3		4 mm	180 mm / 7"		
	ET1 = EA	5000	Type I			160 111117 7		
	ET6 = EC	20 000			4 mm	330 mm / 13"		
TNPW2010 e3	E75 = EY	1000	Blister tape					
TNPW2512 e3	E75 = EY	1000	acc. IEC 60286-3	12 mm	4 mm	180 mm / 7"		
	E67 = EG	2000	туре п					

#### Note

#### **DESCRIPTION**

Production is strictly controlled and follows an extensive set of instructions established for reproducibility. A homogeneous film of metal alloy is deposited on a high grade Al<sub>2</sub>O<sub>3</sub> ceramic substrate and conditioned to achieve the desired temperature coefficient. Specially designed inner contacts are deposited on both sides. A special laser is used to achieve the target value by smoothly fine trimming the resistive layer without damaging the ceramics. A further conditioning is applied in order to stabilize the trimming result. The resistor elements are covered by a protective coating designed for electrical, mechanical and climatic protection. The terminations receive a final pure tin on nickel plating. The result of the determined production is verified by an extensive testing procedure on 100 % of the individual chip resistors. This includes pulse load screening for the elimination of products with a potential risk of early life failures according to EN 140401-801, 2.1.2.2. Only accepted products are laid directly into the tape in accordance with EN 60286-3.

#### **ASSEMBLY**

The resistors are suitable for processing on automatic SMD assembly systems. They are suitable for automatic soldering using wave, reflow or vapour phase as shown in **IEC 61760-1**. The encapsulation is resistant to all cleaning solvents commonly used in the electronics industry, including alcohols, esters and aqueous solutions. The suitability of conformal coatings, if applied, shall be qualified by appropriate means to ensure the long-term stability of the whole system. The resistors are RoHS compliant, the pure tin plating provides compatibility with lead (Pb)-free and lead-containing soldering processes. The immunity of the plating against tin whisker growth has been proven under extensive testing.

All products comply with the GADSL (2) and the CEFIC-EECA-EICTA (3) list of legal restrictions on hazardous substances. This includes full compliance with the following directives:

- 2000/53/EC End of Vehicle life Directive (ELV) and Annex II (ELV II)
- 2011/65/EU Restriction of the use of Hazardous Substances Directive (RoHS)
- 2002/96/EC Waste Electrical and Electronic Equipment Directive (WEEE)

The resistors are Halogen-free according to JEDEC JS709A definition.

Solderability is specified for 2 years after production or re-qualification. The permitted storage time is 20 years.

### **RELATED PRODUCTS**

The TNPW with SnPb termination plating is designed for those applications, where lead bearing terminations are mandatory. For ordering TNPW with SnPb terminations please refer to latest edition of data sheet TNPW, document number 31006.

TNPS .... ESCC high-reliability thin film chip resistors are the premium choice for design and manufacture of equipment, where matured technology and proven reliability are of utmost importance. They are regularly used in communication and research satellites and fit equally well into aircraft and military electronic systems. Approval of the TNPS .... ESCC products is granted by the European Space Components Coordination and registered in the ESCC Qualified Parts List, REP005, document number 28789.

#### **Notes**

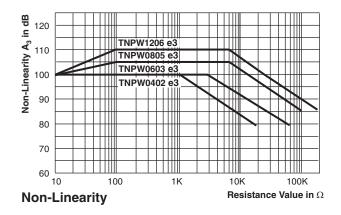
(2) Global Automotive Declarable Substance List, see www.gadsl.org.

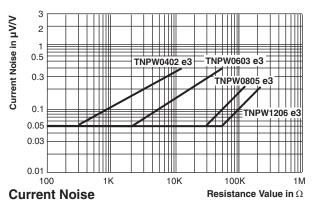
<sup>(1) 1000</sup> pieces packaging is available only for precision resistors with tolerance ± 0.1 % and temperature coefficient ≤ ± 25 ppm/K.

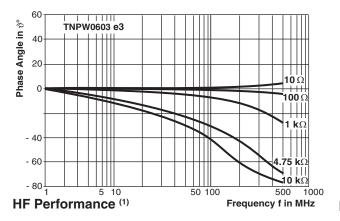
<sup>(3)</sup> CEFIC (European Chemical Industry Council), EECA (European Electronic Component Manufacturers Association), EICTA (European trade organisation representing the information and communications technology and consumer electronics), see <a href="www.eicta.org">www.eicta.org</a> → issue → environment policy → chemicals → chemicals for electronics.

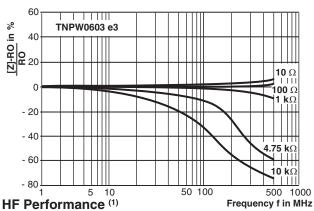


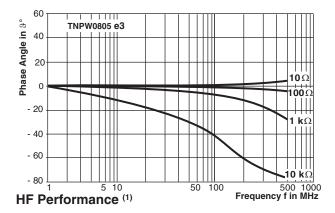
#### **FUNCTIONAL PERFORMANCE**

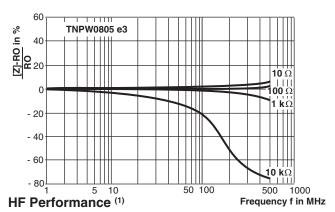












#### Note

(1) Typical figures. HF-characteristic also depends on termination and circuit design.

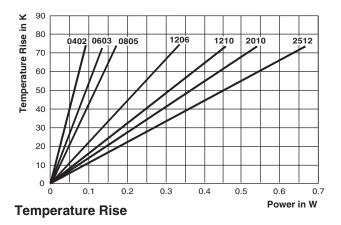
www.vishay.com 340 For technical questions, contact: <a href="mailto:thinfilmchip@vishay.com">thinfilmchip@vishay.com</a>

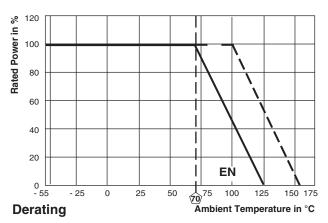
Document Number: 28758

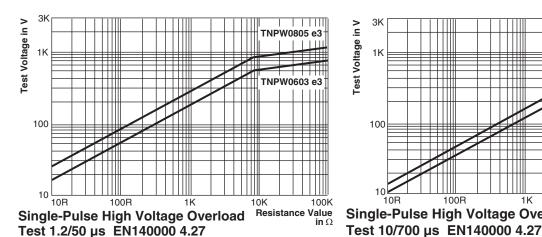
Revision: 27-Jun-12

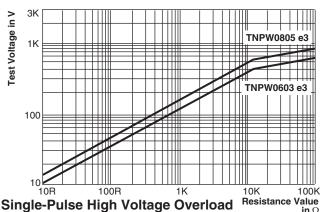


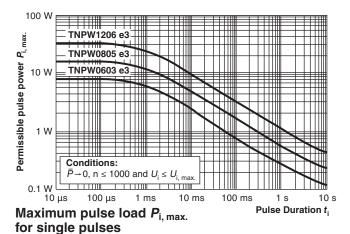


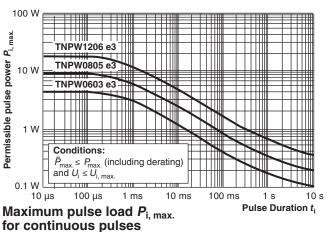








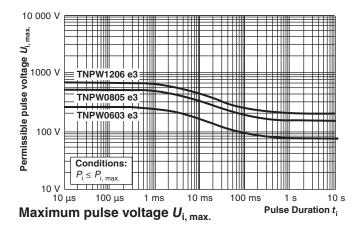




Document Number: 28758 Revision: 27-Jun-12

For technical questions, contact: thinfilmchip@vishay.com





### **TEST AND REQUIREMENTS**

All tests are carried out in accordance with the following specifications:

IEC 60115-1, generic specification (includes tests)

EN 140400, sectional specification (includes schedule for qualification approval)

EN 140401-801, detail specification (includes schedule for conformance inspection)

The testing also covers most of the requirements specified by EIA/IS-703 and JIS-C-5202. The tests are carried out under standard atmospheric conditions in accordance with IEC 60068-1, 5.3. Climatic category LCT/UCT/56 (rated temperature range: Lower category temperature, upper category temperature; damp heat, long term, 56 days) is valid. Unless otherwise specified the following values apply:

Temperature: 15 °C to 35 °C Relative humidity: 45 % to 75 %

Air pressure: 86 kPa to 106 kPa (860 mbar to 1060 mbar).

The components are mounted for testing on boards in accordance with EN 60115-1, 4.31 unless otherwise specified. The parameters stated in the Test Procedures and Requirements table are based on the required tests and permitted limits of EN 140401-801.

TEST PR	TEST PROCEDURES AND REQUIREMENTS							
EN 60115-1 CLAUSE	IEC 60068-2 TEST METHOD	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE				
			Stability for product types:					
			TNPW0402 e3					
			TNPW0603 e3					
			TNPW0805 e3					
			TNPW1206 e3					
			TNPW1210 e3					
			TNPW2010 e3					
			TNPW2512 e3					
4.5	-	Resistance		± 1 %; ± 0.5 %; ± 0.1 %				
4.8.4.2	-	Temperature coefficient	At (20/- 55/20) °C and (20/125/20) °C	± 50 ppm/K; ± 25 ppm/K; ± 15 ppm/K; ± 10 ppm/K				
		Endurance at	$U = \sqrt{P_{70} \times R}$ or $U = U_{\text{max.}}$ ; whichever is the less severe;					
4.25.1 -	70 °C	1.5 h on; 0.5 h off;						
			70 °C; 1000 h	$\pm$ (0.05 % $R$ + 0.01 $\Omega$ )				
			70 °C; 8000 h	$\pm (0.1 \% R + 0.02 \Omega)$				
4.25.3	-	Endurance at upper category temperature	125 °C; 1000 h 155 °C; 1000 h	± (0.05 % R + 0.01 Ω) ± (0.1 % R + 0.02 Ω)				

www.vishay.com 342

For technical questions, contact: thinfilmchip@vishay.com



EN 60115-1	IEC 60068-2			REQUIREMENTS
CLAUSE	TEST METHOD	TEST	PROCEDURE	PERMISSIBLE CHANGE
			Stability for product types:	
			TNPW0402 e3	
			TNPW0603 e3	
			TNPW0805 e3	
			TNPW1206 e3	
			TNPW1210 e3	
			TNPW2010 e3	
			TNPW2512 e3	
4.24	78 (Cab)	Damp heat, steady state	(40 ± 2) °C; 56 days; (93 ± 3) % RH	± (0.1 % R + 0.01 Ω)
4.23		Climatic sequence:		
4.23.2	2 (Bb)	Dry heat	UCT; 16 h	
4.23.3	30 (Db)	Damp	55 °C; 24 h; > 90 % RH; 1 cycle	
4.23.4	1 (Ab)	Cold	LCT; 2 h	± (0.1 % R + 0.02 Ω)
4.23.5	13 (M)	Low air	8.5 kPa; 2 h; 25 ± 10 °C	± (0.1 /0 // + 0.02 32)
4.23.6	30 (Db)	Damp heat, cyclic	55 °C; 5 days; > 95 to 100 % RH; 5 cycles	
4.23.7	-	DC load	$U = \sqrt{P_{70} \times R} \le U_{\text{max}}; 1 \text{ min}$ $LCT = -55 \text{ °C}$ $UCT = 125 \text{ °C}$	
-	1 (Ab)	Cold	- 55 °C; 2 h	± (0.05 % R + 0.01 Ω)
4.19	14 (Na)	Rapid change of temperature	30 min at LCT and 30 min at UCT; LCT = -55 °C; UCT = 125 °C; 1000 cycles	± (0.1 % R + 0.01 Ω)
4.13	-	Short time overload	$U = 2.5 \times \sqrt{P_{70} \times R}$ or $U = 2 \times U_{\text{max}}$ ; whichever is the less severe; 5 s	± (0.05 % R + 0.01 Ω)
4.27	-	Single pulse high voltage overload	Severity no. 4: $U = 10 \text{ x } \sqrt{P_{70} \text{ x } R}$ or $U = 2 \text{ x } U_{\text{max}}$ ; whichever is the less severe; 10 pulses 10 µs/700 µs	$\pm$ (0.5 % $R$ + 0.05 $\Omega$ ) no visible damage
4.37	-	Periodic electric overload	$U = \sqrt{15 \times P_{70} \times R} \text{ or } $ $U = 2 \times U_{\text{max}};$ whichever is the less severe; $0.1 \text{ s on; } 2.5 \text{ s off;}$ $1000 \text{ cycles}$	$\pm$ (0.5 % $R$ + 0.05 $\Omega$ ) no visible damage
4.22	6 (Fc)	Vibration	Endurance by sweeping; 10 Hz to 2000 Hz; no resonance; amplitude ≤ 1.5 mm or ≤ 200 m/s²; 7.5 h	$\pm$ (0.05 % $R$ + 0.01 $\Omega$ ) no visible damage

# Vishay

# High Stability Thin Film Flat Chip Resistors



TEST PR	OCEDURES	AND REQUI	REMENTS			
EN 60115-1 CLAUSE	IEC 60068-2 TEST METHOD	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE		
			Stability for product types:			
			TNPW0402 e3			
			TNPW0603 e3			
			TNPW0805 e3			
			TNPW1206 e3			
			TNPW1210 e3			
			TNPW2010 e3			
			TNPW2512 e3			
			Solder bath method; SnPb40; non-activated flux $(215 \pm 3)$ °C; $(3 \pm 0.3)$ s	Good tinning (≥ 95 % covered);		
4.17.2	4.17.2 58 (Td)	Solderability	Solderability	Solderability	Solder bath method; SnAg3Cu0.5 or SnAg3.5; non-activated flux (235 ± 3) °C; (2 ± 0.2) s	no visible damage
4.18.2	58 (Td)	Resistance to soldering heat	Solder bath method; $(260 \pm 5)$ °C; $(10 \pm 1)$ s	± (0.02 % R + 0.01 Ω)		
4.29	45 (XA)	Component solvent resistance	Isopropyl alcohol + 50 °C; method 2	No visible damage		
4.32	21 (Ue <sub>3</sub> )	Shear	RR 1005M and RR 1608M; 9 N	No visible damage		
4.02	21 (063)	(adhesion)	RR 2012M and RR 3216M: 45 N	No visible damage		
4.33	21 (Ue <sub>1</sub> )	Substrate bending	Depth 2 mm, 3 times	$\pm$ (0.05 % $R$ + 0.01 $\Omega)$ no visible damage, no open circuit in bent position		
4.7	-	Voltage proof	$U_{RMS} = U_{ins}$ ; 60 ± 5 s	No flashover or breakdown		
4.35	-	Flammability	IEC 60695-11-5, needle flame test; 10 s	No burning after 30 s		
-	-	Damp heat	(85 ± 5) °C; 56 days (85 ± 5) % RH	± (0.25 R + 0.05 Ω)		



### **Legal Disclaimer Notice**

Vishay

### **Disclaimer**

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

# **Material Category Policy**

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.

Revision: 02-Oct-12 Document Number: 91000

# **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Thin Film Resistors - SMD category:

Click to view products by Vishay manufacturer:

Other Similar products are found below:

```
M55342K06B34E0RT3 D55342E07B379BR-TR AR02BTC1872 AR02BTC18R7 AR02BTC3830 AR02BTC4220 AR02BTC4222

AR02BTC5100 AR02BTC5111 AR02BTC5762 AR02BTC8251 AR02BTC8452 AR03BTC0110 AR03BTC0120 AR03BTC0330

AR03BTC0390 AR03BTC1102 AR03BTC1103 AR03BTC1201 AR03BTC2000 AR03BTC2201 AR03BTC2203 AR03BTC2490

AR03BTC3003 AR03BTC3302 AR03BTC3901 AR03BTC4220 AR03BTC4223N AR03BTC5602 AR03BTC5603 AR03BTC5900

AR03BTC7500 AR03BTC9100 AR03BTC9103 AR03BTC9760 AR05BTC0280 AR05BTC1000 AR05BTC1100 AR05BTC1201

AR05BTC1202 AR05BTC1300 AR05BTC14R3 AR05BTC1500 AR05BTC1523 AR05BTC1620 AR05BTC1623

AR05BTC1760 AR05BTC1800 AR05BTC1823
```